

LTM4627-BGA, 133LD 15mm X 15mm X 4.92mm (TABLE OF MATERIAL DECLARATION)							
The LTM4627 is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2329	Barium Compounds	7727-43-7	0.00629	2.70
				Filler Sumstances (Crystalline Silica)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2	0.06680	28.69
				Copper Metal	7440-50-8	0.08692	37.33
				Copper Compounds	1328-53-6	0.00005	0.02
				Gold metal or alloy	7440-57-5	0.00084	0.36
				Nickel	7440-02-0	0.00533	2.29
				Zinc	7440-66-6	0.00007	0.03
				Bisphenol A epoxy resin	25068-38-6	0.00002	0.01
				Continuous Filament Fiber Glass	65997-17-3	0.05248	22.54
				Acrylic Resin	non-disclosure	0.01199	5.15
				Epoxy Resin	non-disclosure	0.00015	0.07
				Silica Amorphous	7631-86-9	0.00008	0.03
				Talc;not containing fibers like asbestors	14807-96-6	0.00072	0.31
				Aromatic carbonyl compounds	non-disclosure	0.00068	0.29
				Cyanoguanidine	461-58-5	0.00002	0.01
				Amine compounds	non-disclosure	0.00009	0.04
				Leveling agent and others	non-disclosure	0.00028	0.12
				Imidazole system curing reagent	non-disclosure	0.00002	0.01
2	Solder Paste	Alloy	0.0201	Sn	7440-31-5	0.01913	95.00
				Sb	7440-36-0	0.00101	5.00
3	Passive/Active Components		0.8898	Iron Powder (Fe)	7439-89-6	0.5030	56.53
				Copper (Cu)	7440-50-8	0.2028	22.79
				Nickel (Ni)	7440-02-0	0.0217	2.44
				Tin (Sn)	7440-31-5	0.0102	1.14
				Ceramic (Ba) Compounds	12047-27-7	0.1521	17.09
4	Active Ics	Silicon	0.0111	Silicon	7440-21-3	0.01112	100.00
5	Wire	Gold	0.0022	Au	7440-57-5	0.00220	99.99
4	Solder Ball		0.2234	Sn	7440-31-5	0.21558	96.50
				Ag	7440-22-4	0.00670	3.00
				Cu	7440-50-8	0.00112	0.50
6	Encapsulation	Epoxy Resin	1.4707	Fused Silica	60676-86-0	1.13535	77.20
				Epoxy Resin	non-disclosure	0.13089	8.90
				Phenol Resin	non-disclosure	0.13089	8.90
				Crytalline Silica	14808-60-7	0.04412	3.00
				Carbon Black	1333-86-4	0.00735	0.50
				Metal Hydroxide	non-disclosure	0.02206	1.50
Total Package Weight			2.8502				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts